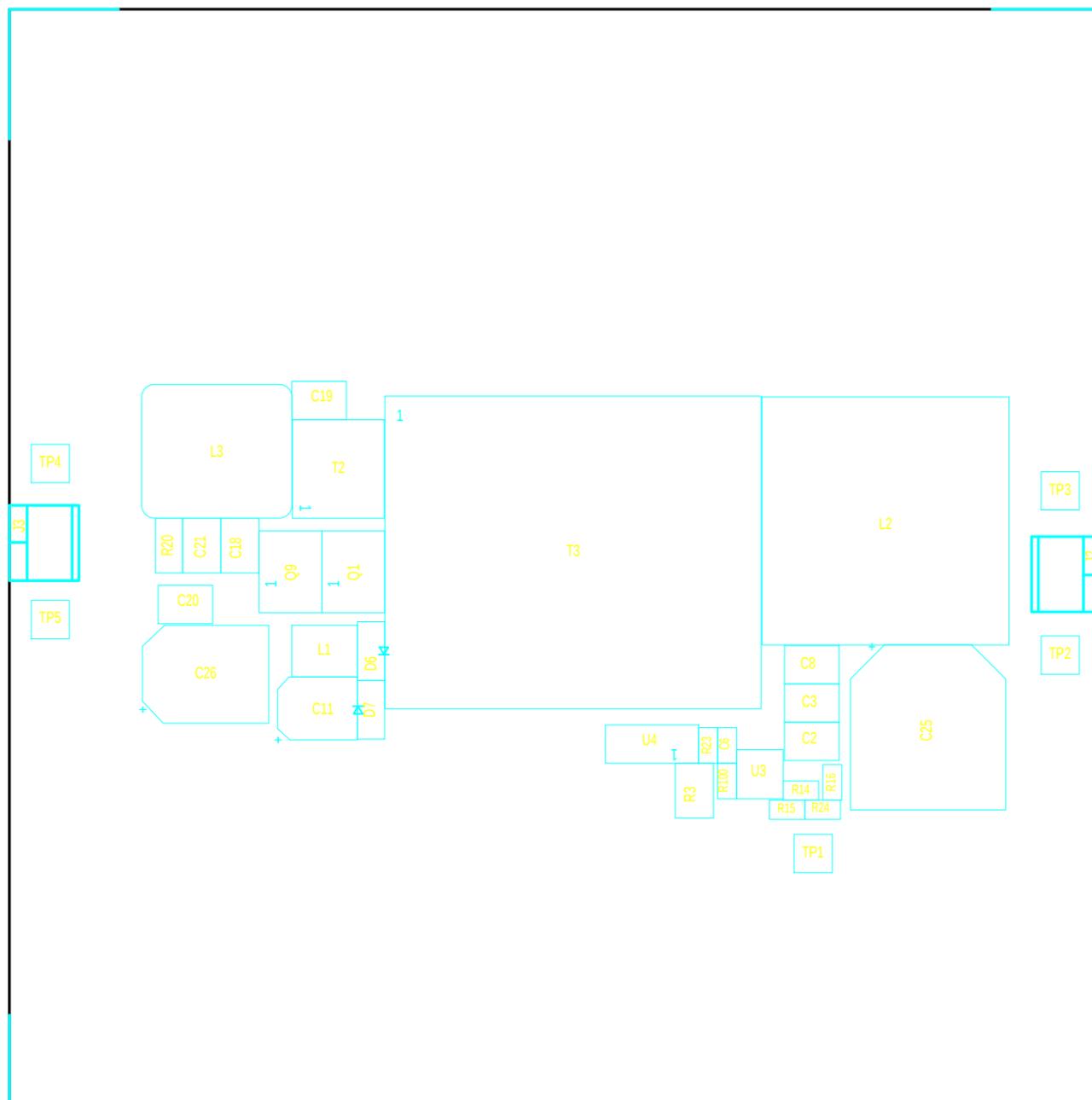
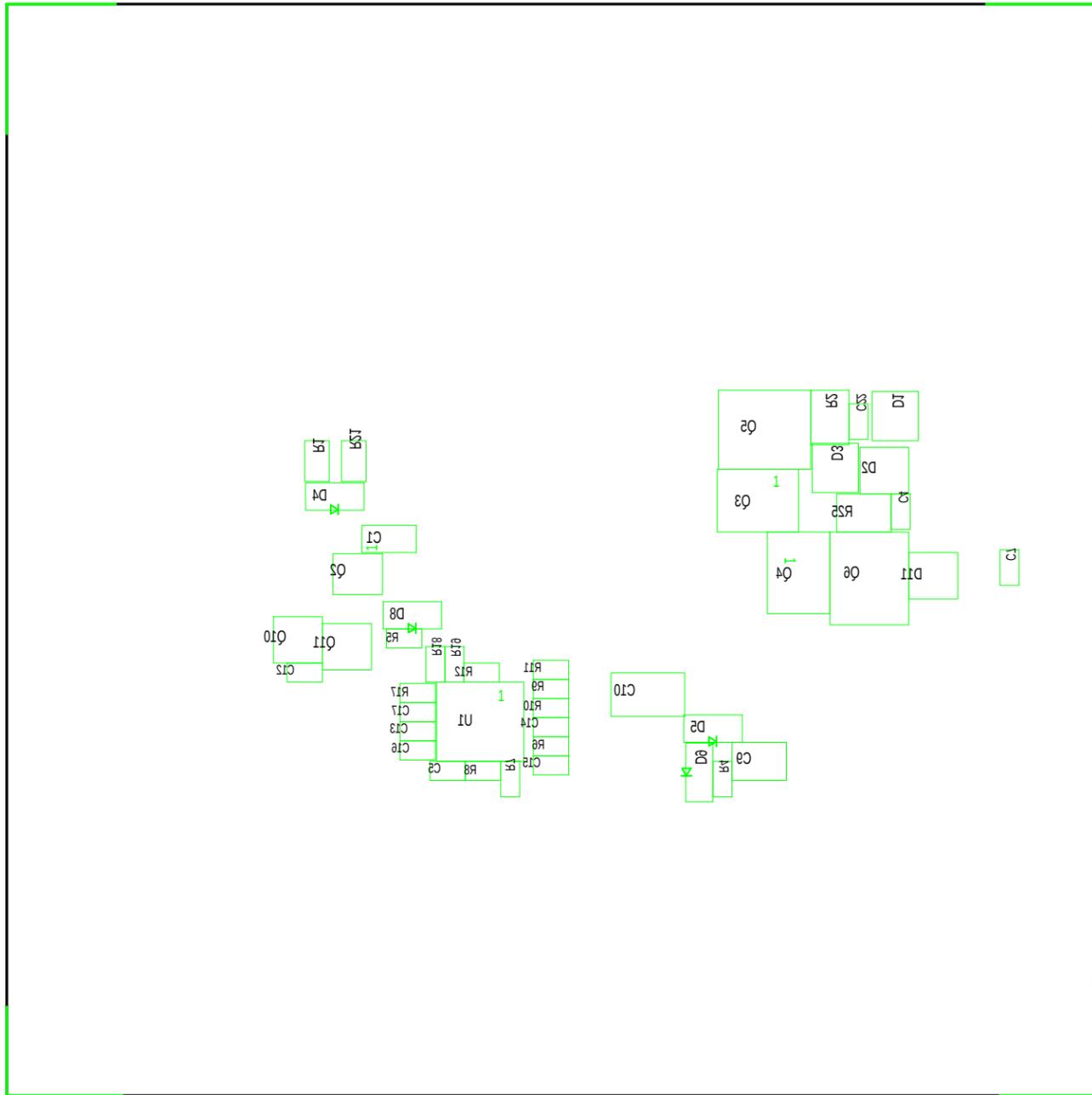


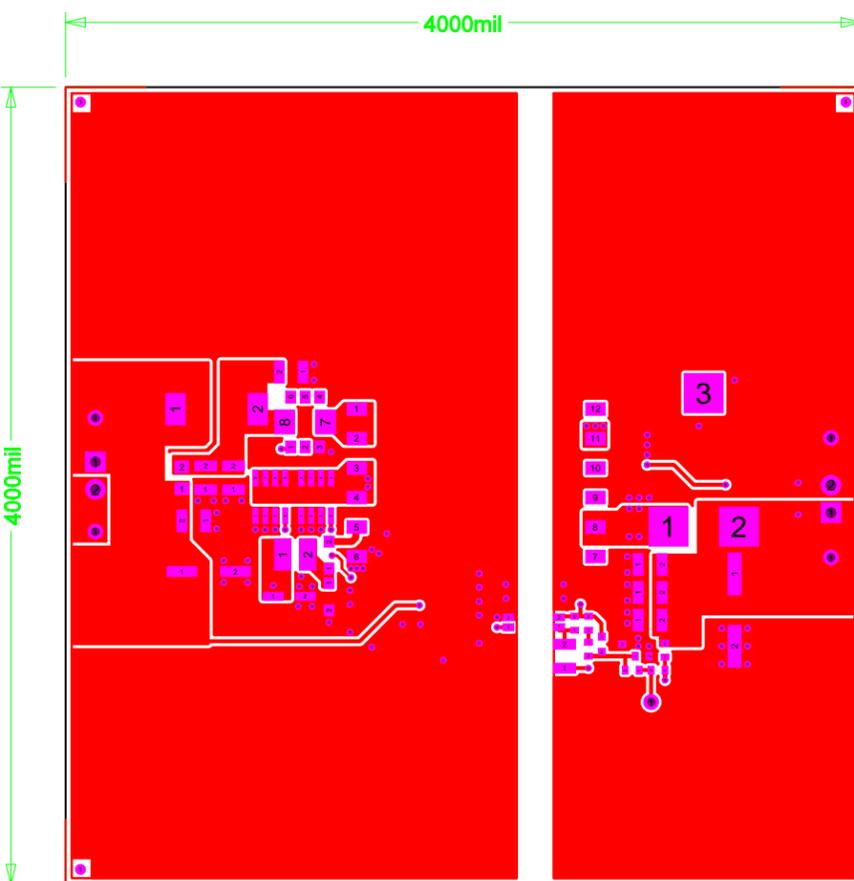
TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP7294	Rev.	A	L1								
Date: {Start Date}	Filename: PMP7294_REVA.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}								Software PADs v9.3



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP7294	Rev.	A	L1						TA		
Date: {Start Date}	Filename: PMP7294_REVA.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}						Software	PADs v9.3	



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP7294	Rev.	A								BA	
Date: {Start Date}	Filename: PMP7294_REVA.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}				Software	PADs v9.3			



FABRICATION CHART			
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
<input type="checkbox"/> 0.031 <input checked="" type="checkbox"/> 0.062 <input type="checkbox"/> 0.093 <input type="checkbox"/> 0.125	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____
DESIGN	TRACE/GAP SPACING	LAYER COUNT	
<input type="checkbox"/> SMD <input type="checkbox"/> THRU-HOLE <input checked="" type="checkbox"/> MIX	<input checked="" type="checkbox"/> 0.010/0.010 <input type="checkbox"/> 0.008/0.007 <input type="checkbox"/> 0.006/0.006	<input type="checkbox"/> SINGLE SIDED <input checked="" type="checkbox"/> 2 LAYER <input type="checkbox"/> 4 LAYER <input type="checkbox"/> OTHER _____	

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
- BASE LAMINATE:** EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
- TOLERANCES:** UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
- PLATING:** HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
- WORKMANSHIP:** BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
Board No.	Rev.	Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
PMP7294	A	L1										FB
Date: (Start Date)	Filename: PMP7294_REVA.PCB	Engineer: B.KING	PCB Design: R.SMITH	Modified Date: (Modification Date)				Software: PADS v9.3				

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